

# KY DMLS31.FY

## SYNIOS® P2720

This compact LED device is part of the SYNIOS P2720 family. Given the scalability of this product family, it provides full performance and flexibility with just one footprint.

The KY DMLS31.FY product is meant to provide superior light quality in 1 mm<sup>2</sup> chip size class.



## Applications

- Signalling

## Features:

- Package: SMD epoxy package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.57, Cy = 0.42 acc. to CIE 1931 (● converted yellow)
- Corrosion Robustness Class: 3B
- Qualifications: The product qualification test plan is based on the guidelines of IEC60810, Lamps for road vehicles – Performance requirements – Requirements and test conditions for LED packages.
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

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## Ordering Information

Type	Luminous Flux <sup>1)</sup> $I_F = 600 \text{ mA}$ $\Phi_V$	Ordering Code
KY DMLS31.FY-Z8KF8-5F-8E8G	106 ... 180 lm	Q65112A9478

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## Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	$T_{op}$	min.	-40 °C
		max.	125 °C
Storage Temperature	$T_{stg}$	min.	-40 °C
		max.	125 °C
Junction Temperature	$T_j$	max.	150 °C
Junction Temperature for short time applications*	$T_j$	max.	175 °C
Forward Current $T_s = 25\text{ °C}$	$I_F$	min.	20 mA
		max.	700 mA
Surge Current $t \leq 10\ \mu\text{s}$ ; $D = 0.005$ ; $T_s = 25\text{ °C}$	$I_{FS}$	max.	2500 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	$V_{ESD}$		8 kV
Reverse current <sup>2)</sup>	$I_R$	max.	200 mA

\* The median lifetime (L70/B50) for  $T_j = 175\text{ °C}$  is 100h.

## Characteristics

$I_F = 600 \text{ mA}$ ;  $T_s = 25 \text{ °C}$

Parameter	Symbol		Values
Chromaticity Coordinate <sup>3)</sup>	$C_x$	typ.	0.57
	$C_y$	typ.	0.42
Viewing angle at 50% $I_V$	$2\phi$	typ.	120 °
Forward Voltage <sup>4)</sup> $I_F = 600 \text{ mA}$	$V_F$	min.	2.75 V
		typ.	2.95 V
		max.	3.50 V
Reverse voltage (ESD device)	$V_{R\text{ESD}}$	min.	45 V
Reverse voltage <sup>2)</sup> $I_R = 20 \text{ mA}$	$V_R$	max.	1.2 V
Real thermal resistance junction/solderpoint <sup>5)</sup>	$R_{\text{thJS real}}$	typ.	7.0 K / W
		max.	9.0 K / W
Electrical thermal resistance junction/solderpoint <sup>5)</sup> with efficiency $\eta_e = 20 \text{ %}$	$R_{\text{thJS elec.}}$	typ.	5.6 K / W
		max.	7.2 K / W

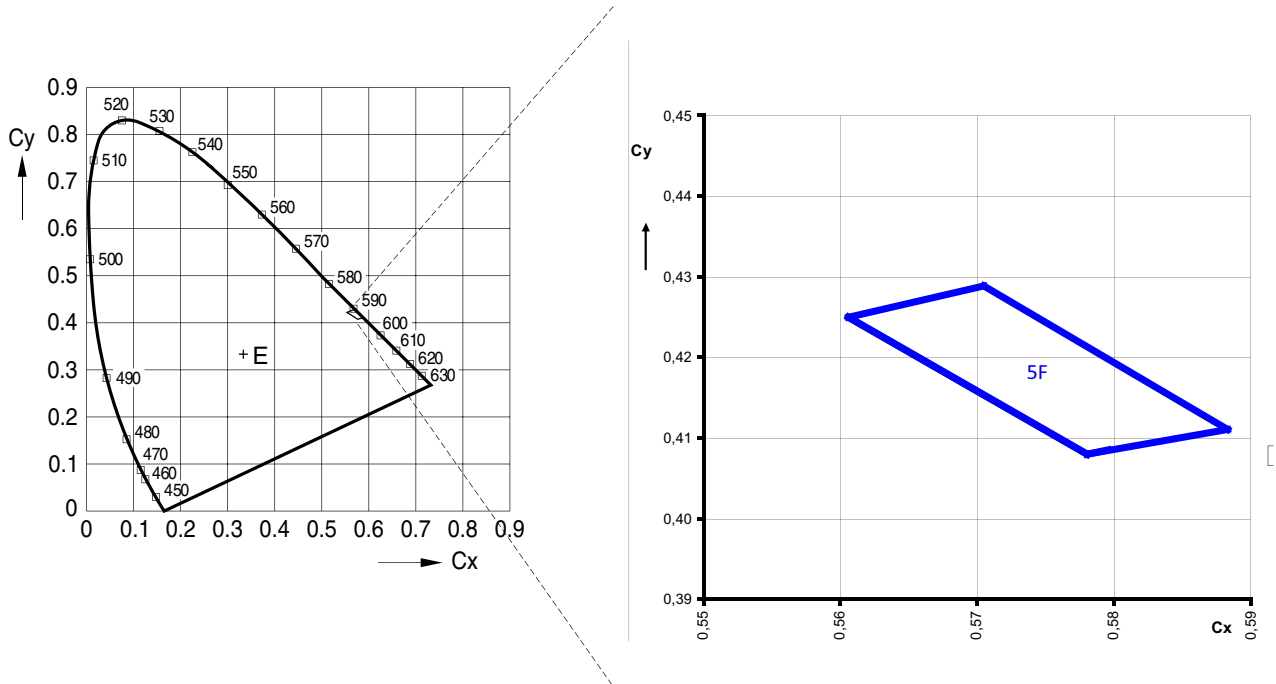
## Brightness Groups

Group	Luminous Flux <sup>1)</sup> $I_F = 600 \text{ mA}$ min. $\Phi_V$	Luminous Flux <sup>1)</sup> $I_F = 600 \text{ mA}$ max. $\Phi_V$	Luminous Intensity <sup>6)</sup> $I_F = 600 \text{ mA}$ typ. $I_v$
8KF	106 lm	118 lm	37 cd
5L	112 lm	125 lm	39 cd
5LF	118 lm	132 lm	41 cd
6L	125 lm	140 lm	44 cd
6LF	132 lm	149 lm	46 cd
7L	140 lm	159 lm	49 cd
7LF	149 lm	169 lm	53 cd
8L	159 lm	180 lm	56 cd

## Forward Voltage Groups

Group	Forward Voltage <sup>4)</sup> $I_F = 600 \text{ mA}$ min. $V_F$	Forward Voltage <sup>4)</sup> $I_F = 600 \text{ mA}$ max. $V_F$
8E	2.75 V	3.00 V
8F	3.00 V	3.25 V
8G	3.25 V	3.50 V

## Chromaticity Coordinate Groups <sup>7)</sup>



## Chromaticity Coordinate Groups <sup>3)</sup>

Group	Cx	Cy
5F	0.5606	0.4250
	0.5705	0.4289
	0.5883	0.4111
	0.5780	0.4080

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## Group Name on Label

**Example: 5L-5F-8E**

Brightness

Color Chromaticity

Forward Voltage

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5L

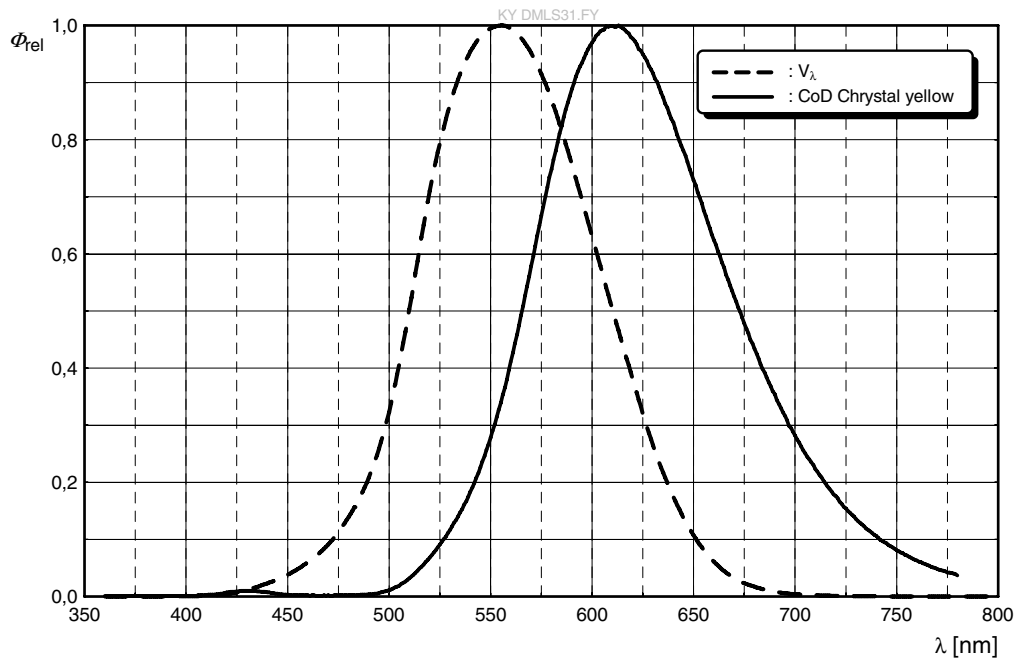
5F

8E

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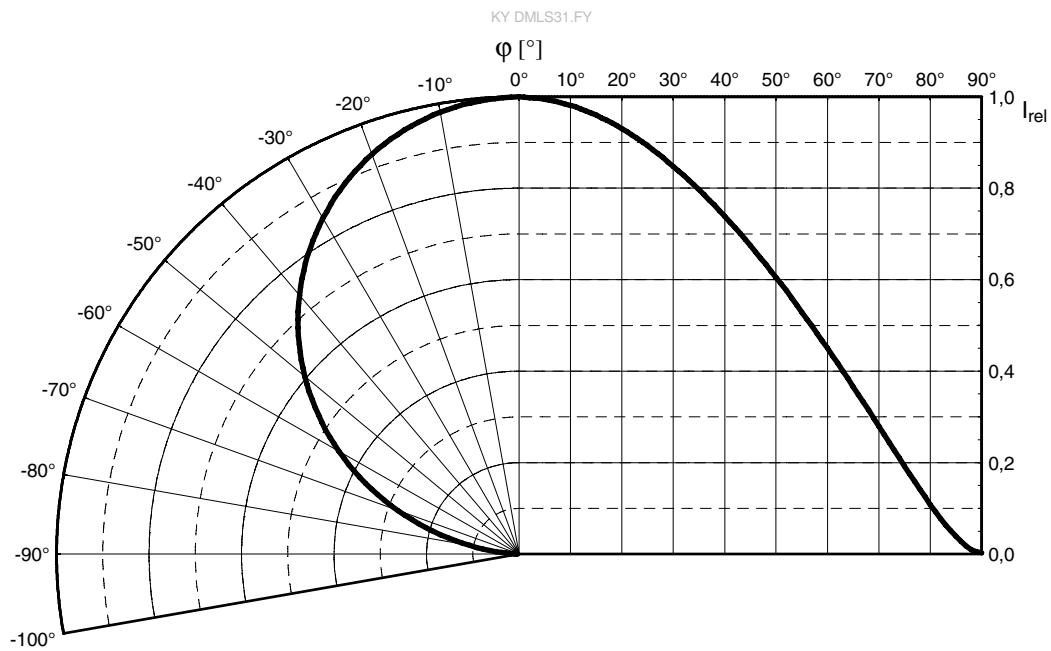
### Relative Spectral Emission <sup>6)</sup>

$\Phi_{rel} = f(\lambda); I_F = 600 \text{ mA}; T_S = 25 \text{ }^\circ\text{C}$



### Radiation Characteristics <sup>6)</sup>

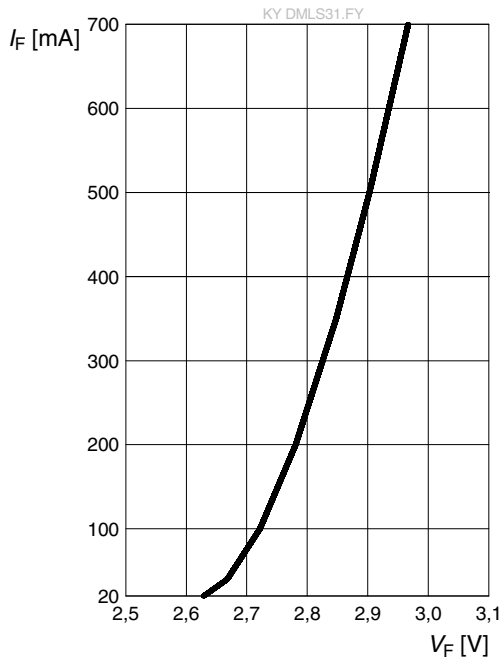
$I_{rel} = f(\phi); T_S = 25 \text{ }^\circ\text{C}$





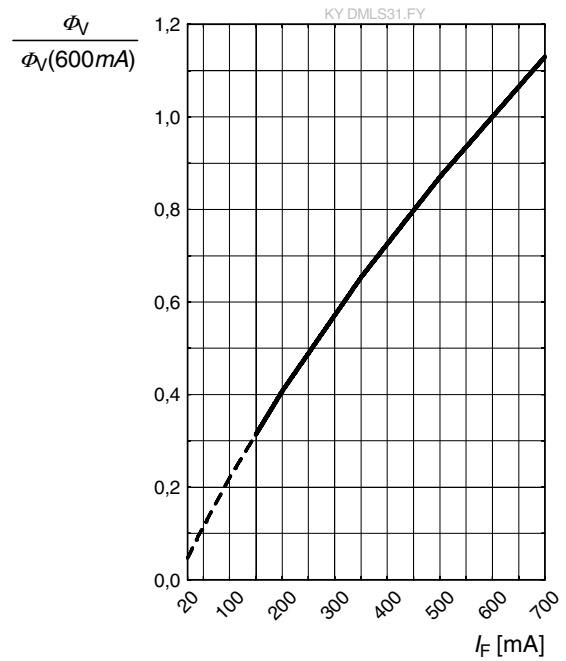
**Forward current** 6), 8)

$I_F = f(V_F); T_S = 25\text{ °C}$



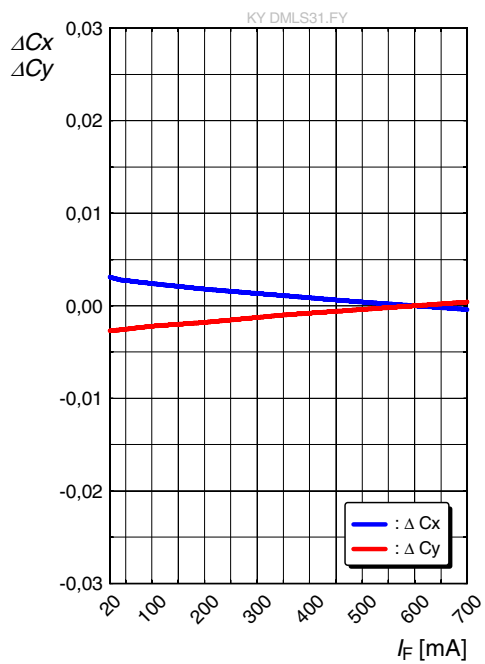
**Relative Luminous Flux** 6), 8)

$\Phi_V / \Phi_V(600\text{ mA}) = f(I_F); T_S = 25\text{ °C}$



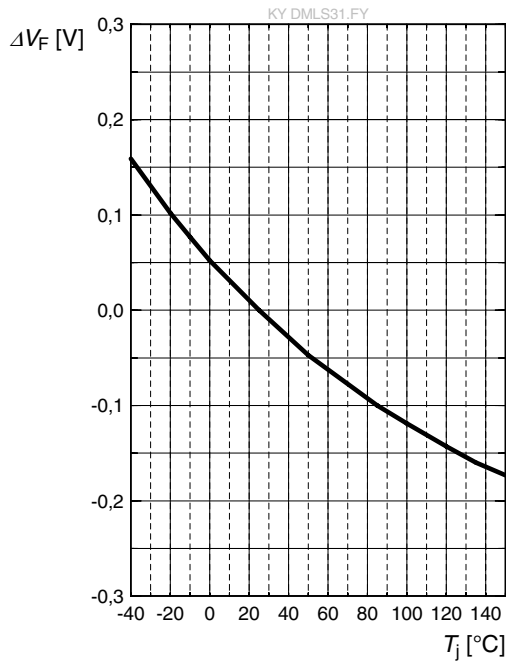
**Chromaticity Coordinate Shift** 6)

$\Delta C_x, \Delta C_y = f(I_F); T_S = 25\text{ °C}$



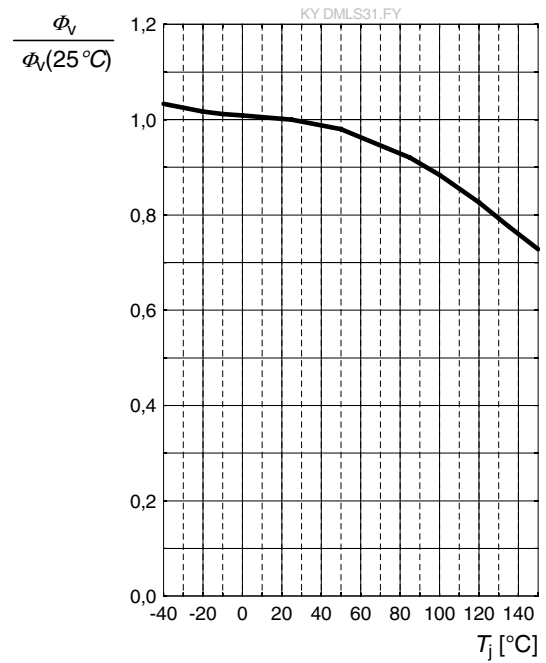
### Forward Voltage <sup>6)</sup>

$$\Delta V_F = V_F - V_F(25\text{ }^\circ\text{C}) = f(T_j); I_F = 600\text{ mA}$$



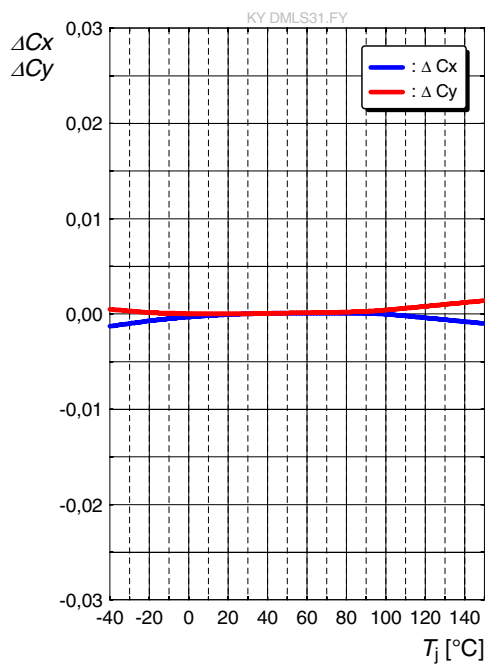
### Relative Luminous Flux <sup>6)</sup>

$$\Phi_V / \Phi_V(25\text{ }^\circ\text{C}) = f(T_j); I_F = 600\text{ mA}$$



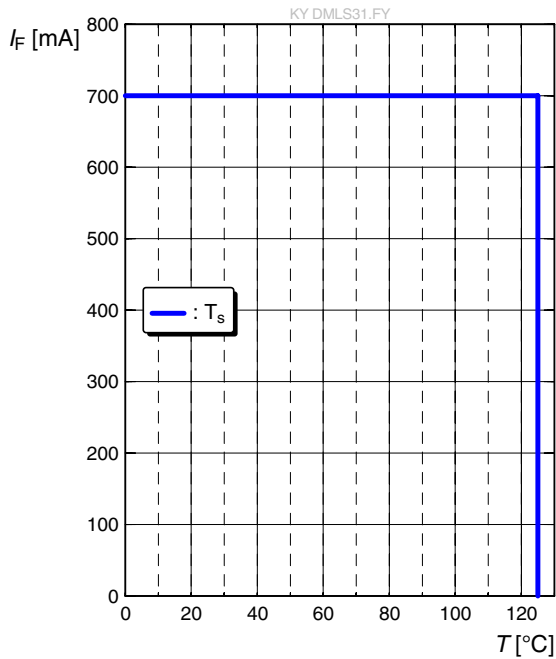
### Chromaticity Coordinate Shift <sup>6)</sup>

$$\Delta C_x, \Delta C_y = f(T_j); I_F = 600\text{ mA}$$



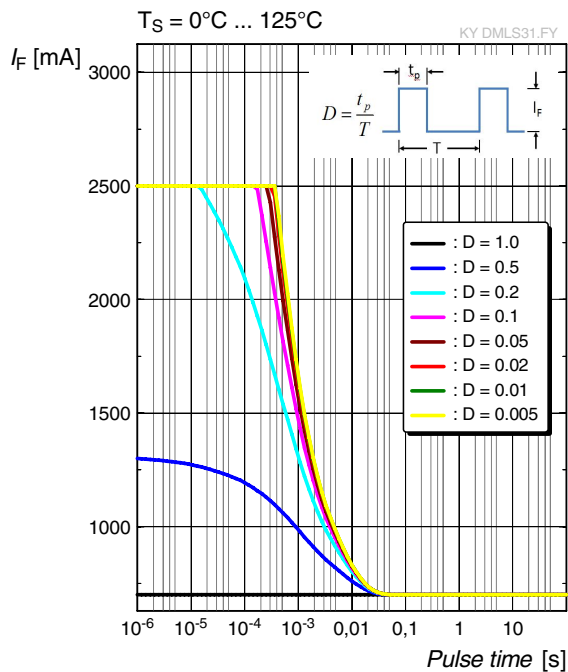
## Max. Permissible Forward Current

$$I_F = f(T)$$

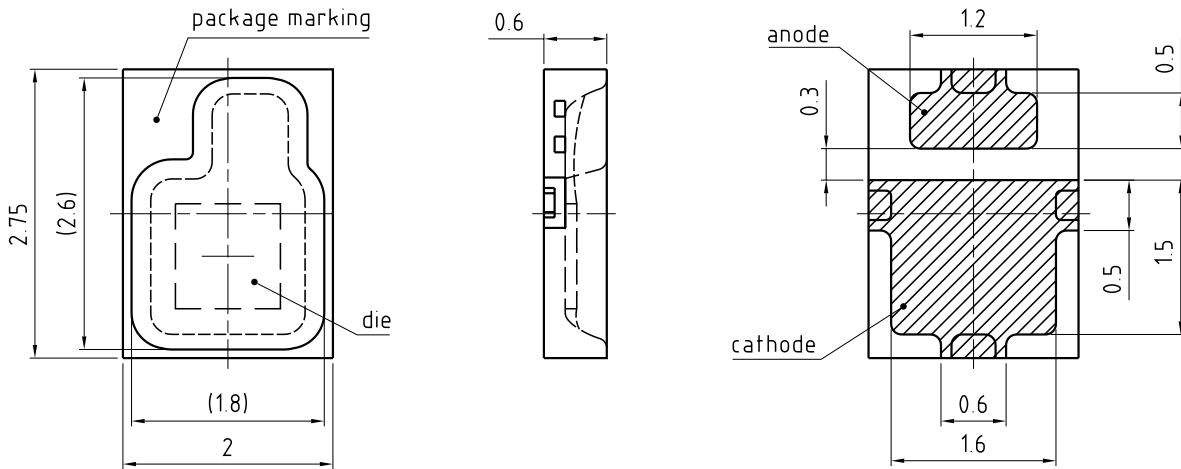


## Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}$$



## Dimensional Drawing <sup>9)</sup>



General tolerance  $\pm 0.1$

Lead finish Au 

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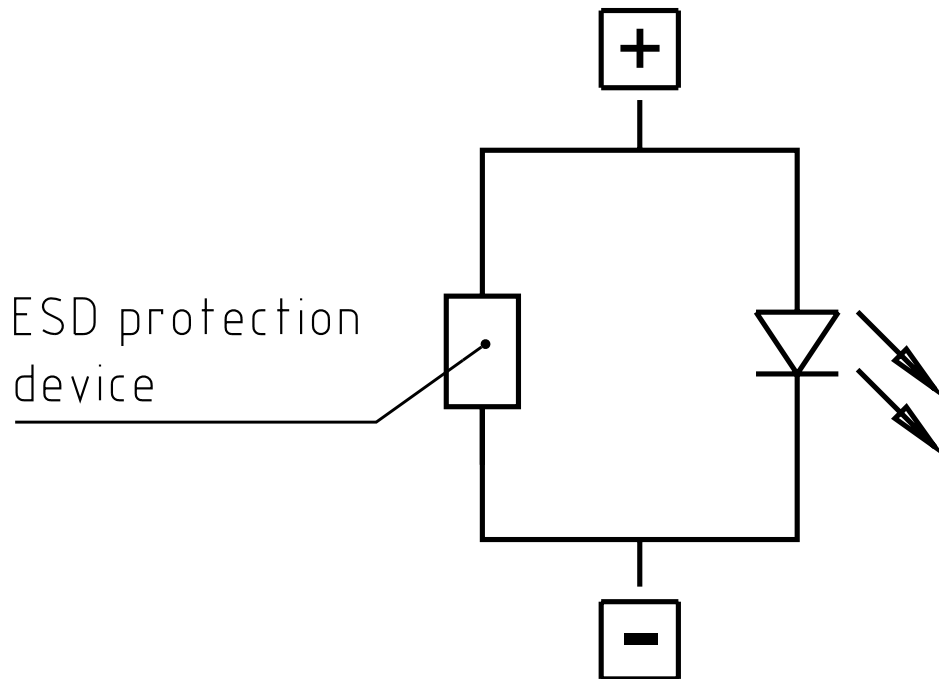
## Further Information

**Approximate Weight:** 12.0 mg

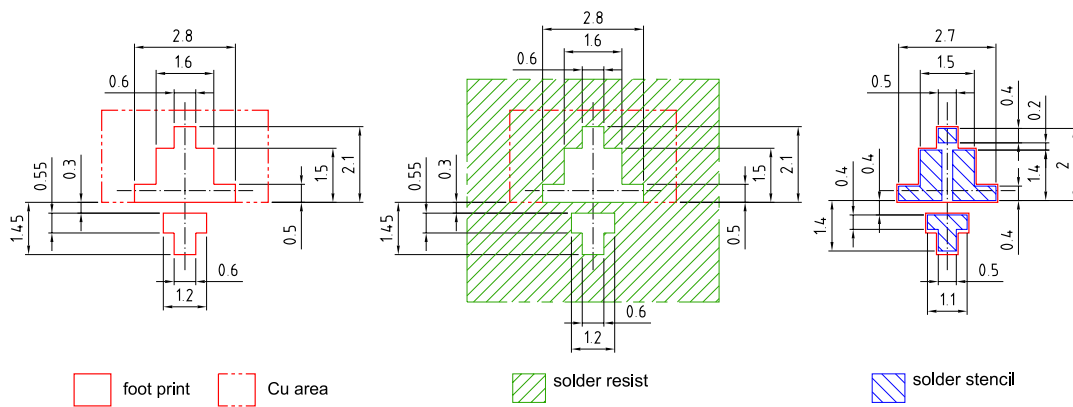
**Corrosion test:** Class: 3B  
 Test condition: 40°C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter than IEC 60068-2-43)

**ESD advice:** The device is protected by ESD device which is connected in parallel to the Chip.

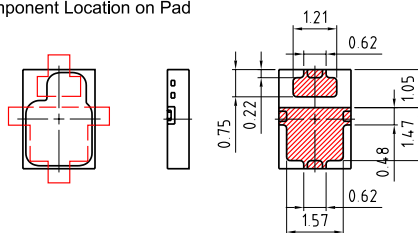
## Electrical Internal Circuit



## Recommended Solder Pad <sup>9)</sup>



Component Location on Pad

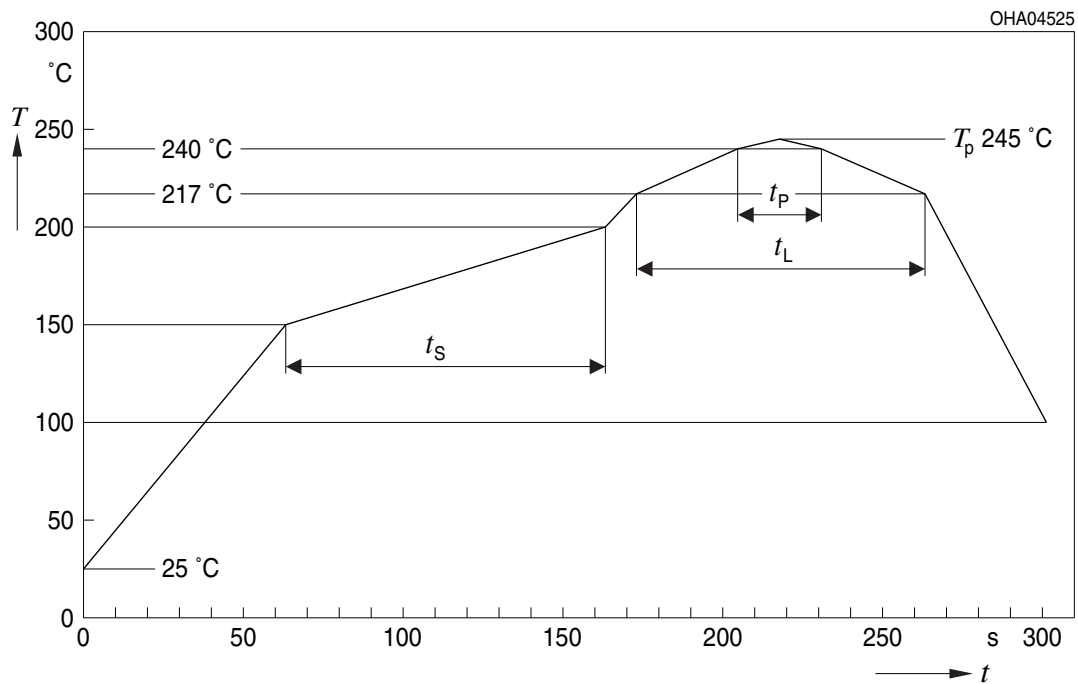


E062.3010.181 -02

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

## Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

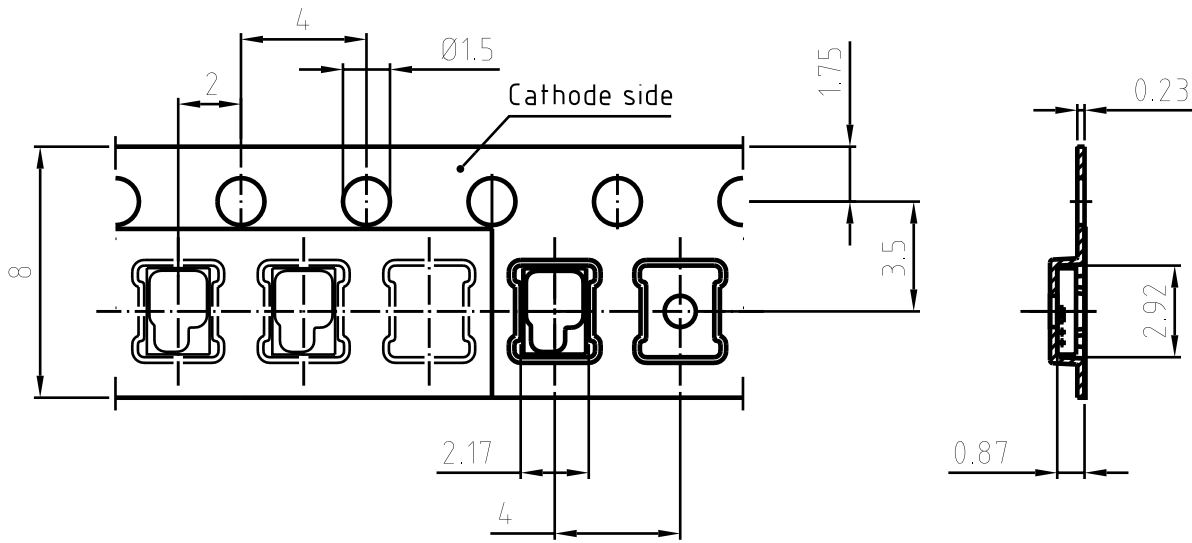


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat <sup>*)</sup> 25 °C to 150 °C			2	3	K/s
Time $t_s$ $T_{Smin}$ to $T_{Smax}$	$t_s$	60	100	120	s
Ramp-up rate to peak <sup>*)</sup> $T_{Smax}$ to $T_p$			2	3	K/s
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_L$		80	100	s
Peak temperature	$T_p$		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	$t_p$	10	20	30	s
Ramp-down rate* $T_p$ to 100 °C			3	6	K/s
Time 25 °C to $T_p$				480	s

All temperatures refer to the center of the package, measured on the top of the component

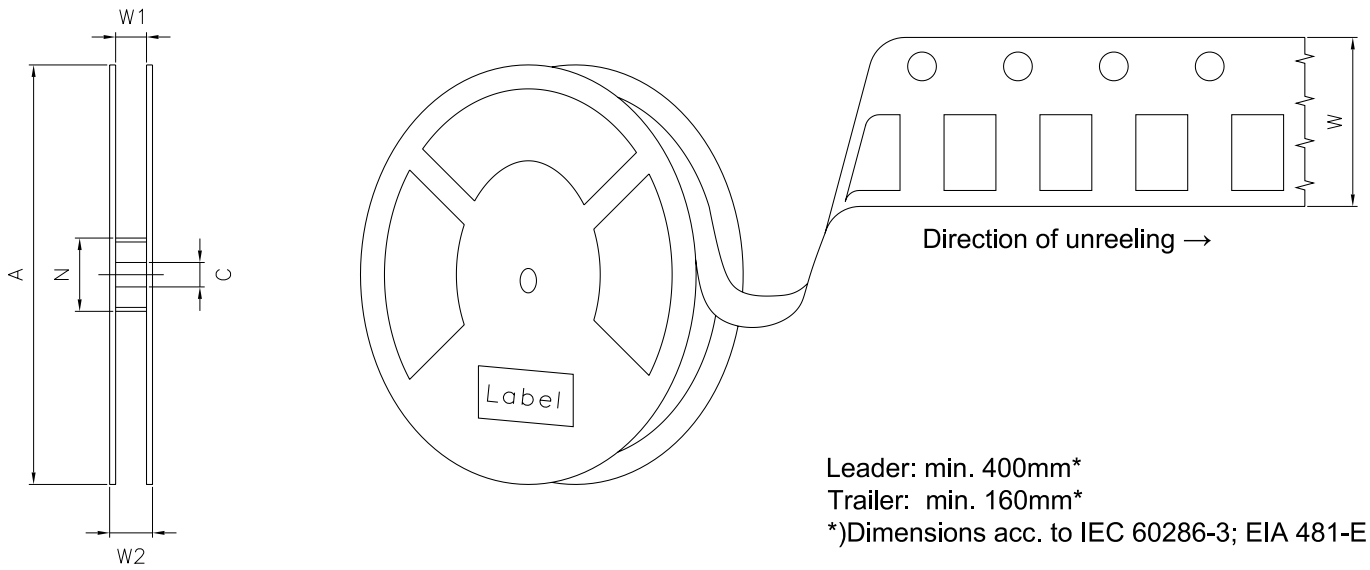
\* slope calculation  $DT/Dt$ :  $Dt$  max. 5 s; fulfillment for the whole T-range

**Taping** <sup>9)</sup>



C67062-A0116-B9-04

**Tape and Reel** <sup>10)</sup>



**Reel Dimensions**

A	W	$N_{min}$	$W_1$	$W_{2max}$	Pieces per PU
180 mm	$8 + 0.3 / - 0.1$ mm	60 mm	$8.4 + 2$ mm	14.4 mm	2000



## Barcode-Product-Label (BPL)

**OSRAM Opto Semiconductors** LX XXXX    BIN1: XX-XX-X-XXX-X


RoHS Compliant

(6P) BATCH NO: 1234567890 ML Temp    ST  
X    XXX °C X

(1T) LOT NO: 1234567890 (9D) D/C: 1234

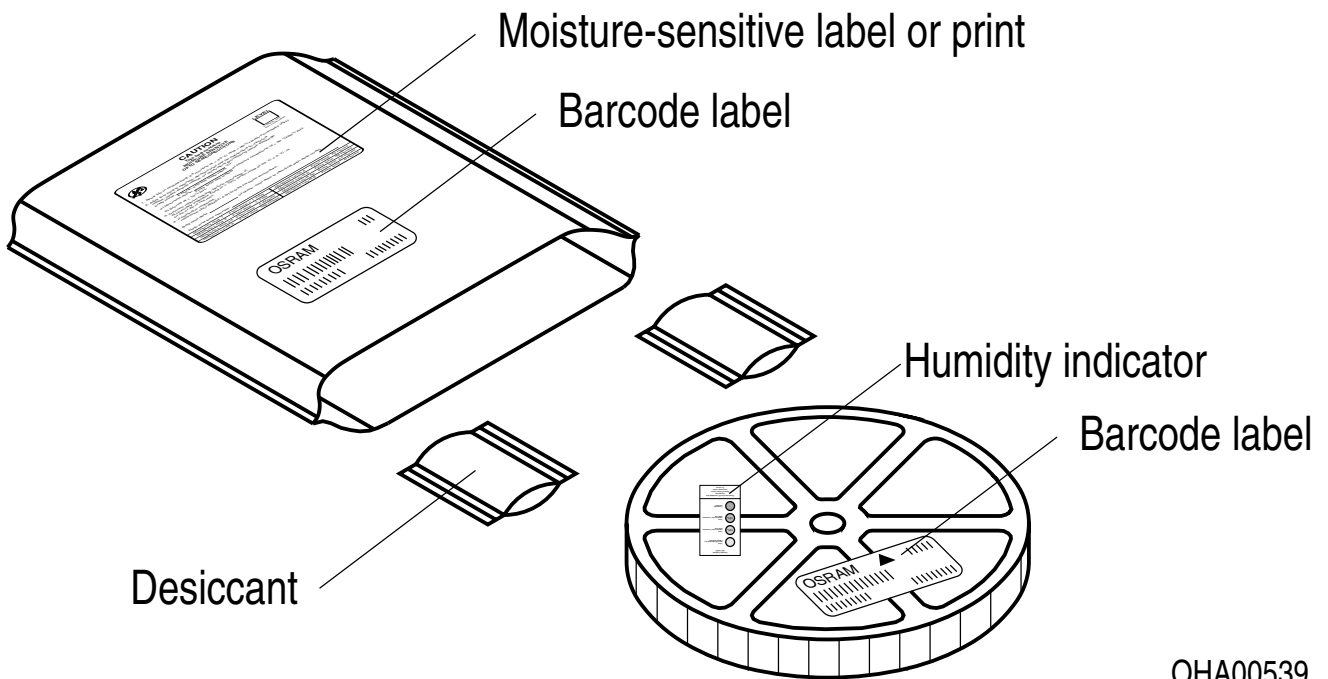
(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

Pack: RXX  
DEMY    XXX  
X\_X123\_1234.1234 X



OHA04563

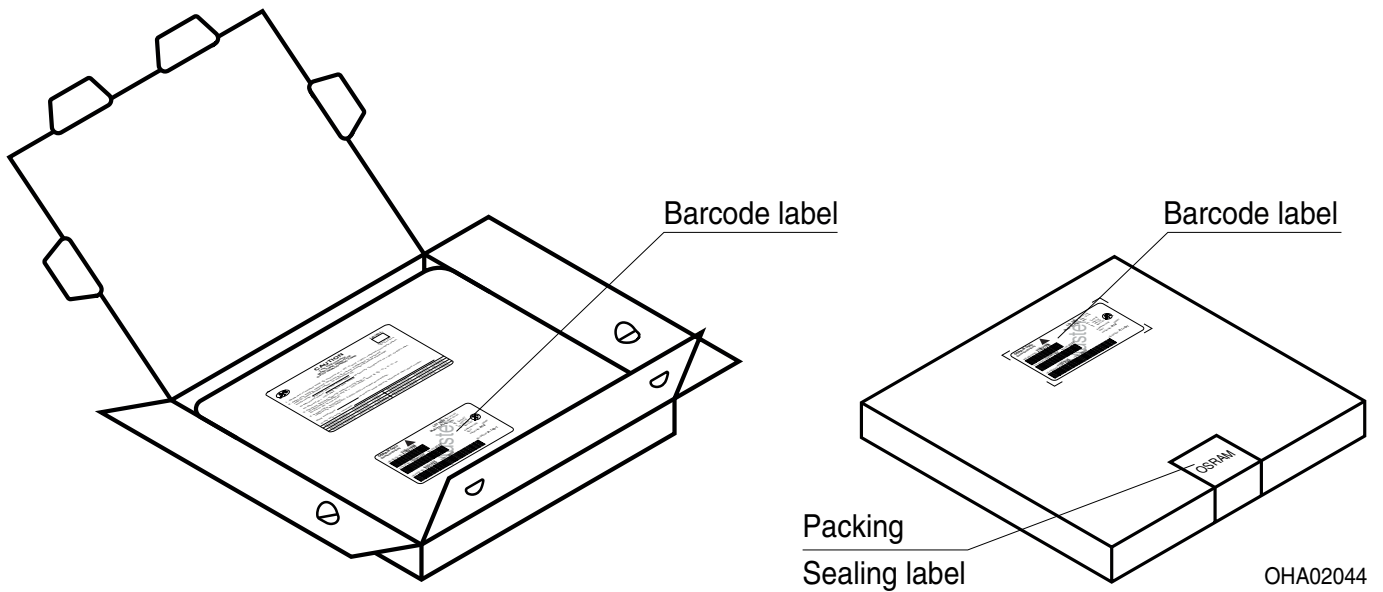
## Dry Packing Process and Materials <sup>9)</sup>



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

## Schematic Transportation Box <sup>9)</sup>



## Dimensions of Transportation Box

Width	Length	Height
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm

## Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit [www.osram-os.com/appnotes](http://www.osram-os.com/appnotes)

## Disclaimer

### **Attention please!**

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

### **Product and functional safety devices/applications or medical devices/applications**

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

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## Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 8\%$  and an expanded uncertainty of  $\pm 11\%$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typical 25 ms, with an internal reproducibility of  $\pm 0.001$  and an expanded uncertainty of  $\pm 0.004$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 4) **Forward Voltage:** Forward voltages are tested at a current pulse duration of 1 ms and a tolerance of  $\pm 0.05\text{ V}$  and an expanded uncertainty of  $\pm 0.1\text{ V}$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 5) **Thermal Resistance:**  $R_{th\ max}$  is based on statistic values ( $6\sigma$ ).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 0.005$  and an expanded uncertainty of  $\pm 0.01$  (acc. to GUM with a coverage factor of  $k = 3$ ).
- 8) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with  $\pm 0.1$  and dimensions are specified in mm.
- 10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

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## Revision History

Version	Date	Change
1.4	2019-08-12	Ordering Information Brightness Groups

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此产品符合欧盟 RoHS 指令的要求；  
按照中国的相关法规和标准，不含有毒有害物质或元素。



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.